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SVTC expands MEMS capabilities

New tools and processes designed to enable next-generation MEMS development

SEMICON, SAN FRANCISCO, (July 14, 2008)—To meet the need for advanced micro-electromechanical systems (MEMS) tools, SVTC Technologies, a leading independent semiconductor process-development foundry, announced that it has expanded its capabilities to enable customers to move toward the next generation of MEMS processing.

In particular, new equipment from Lam Research Corp. and SUSS MicroTec is adding deep silicon etch, wafer bonding, proximity alignment and additional microlithography capabilities at SVTC's facilities. Most MEMS developers still use 5-inch and 6-inch operational fabs, which lack compatibility with advanced CMOS processing equipment and foundries. SVTC offers the latest 200mm (8-inch) CMOS fab tools and processes, making its facilities a valuable R&D asset for MEMS developers.

"MEMS developers are looking for the ability to explore new processes using new materials, and we are committed to supporting the continued advancement of new MEMS structures," said Dave Bergeron, CEO of SVTC Technologies. "While it might be obvious that smaller MEMS developers would appreciate a facility like SVTC's to develop their leading-edge processes and materials, large companies also come here to take advantage of our specialized MEMS equipment for tasks such as pathfinding, product validation and pilot production."

From Lam Research, SVTC offers the TCP® 9400DSiE™ deep silicon etch system. This deep silicon etch tool offers:

- Broad process capability and flexibility for a wide range of MEMS applications, as well as for advanced 3D integration and power semiconductor uses
- Patented TCP plasma source, a planar source that provides exceptionally uniform ion flux without requiring separate source and diffusion chambers – leading to high across-wafer uniformity of etch rate, profile shape and critical dimensions (CDs)
- Process repeatability, high device yield, excellent system productivity and superior process stability for demanding device requirements

"SVTC offers its customers an innovative, cost-effective, real-time environment to accelerate the transfer of MEMS and other emerging technologies from R&D to high-volume production," said Steve Lassig**,** Senior Product Marketing Manager of Lam Research. "Lam Research is a leading supplier of

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high-volume, deep silicon etch tools – which are crucial for the rapidly growing MEMS market. By including our TCP 9400DSiE system in their facilities, SVTC is ideally positioned to spur 200mm wafer MEMS development efforts."

SVTC has added the following equipment from SUSS MicroTec, a leading supplier for process and testing solutions, for MEMS processing as well as post-fab bonding processes:

- CBC200 Automated Bonder (which includes a CB200 high-performance bond module, BA200 bond aligner module and CP200 cool-plate module)
- SB8e Manual Bonder
- MA/BA8 Mask/Bond Aligner, a compact, full-field aligner including topside and backside alignment; flexible wafer handling of 2" to 8" wafers as well as 1"x1" to 8"x8" pieces; and mask sizes up to 9"x9"
- PM8 Manual Prober
- ACS200 Plus Microlithography Cluster (including a spin coater, developer and bake stack), which is used for thick resist applications

"SVTC is providing an increasingly sophisticated environment for MEMS development, as evidenced by our becoming a more integral part of SVTC's MEMS activities," said Stephen Kay, president, North American Sales and Customer Support, for SUSS MicroTec. "Achieving the next generation of MEMS products requires tool sets that are difficult to justify for MEMS developers, during initial prototyping and preproduction. We believe that SVTC will be a crucial enabler of the next wave of important MEMS development on 200mm wafers and we are excited to lend our expertise in the area of MEMS development and manufacturing to this effort."

These new additions enhance SVTC's existing ability to support MEMS development activities. For example, equipment from Aviza, Vesta, Applied Materials and others enables SVTC to offer processes, tools and capabilities including:

- Atomic layer deposition (ALD), including for new materials such as aluminum oxide (Al_2O_3), silicon germanium (SiGe), amorphous silicon (a-Si), amorphous carbon (a-C), and metals such as nickel (Ni) and copper (Cu)
- Low-temperature SiGe
- MEMS masks
- The ability to integrate MEMS structures on top of CMOS wafers

About SVTC

SVTC Technologies, a leading independent semiconductor development foundry, enables the development and commercialization of innovative semiconductor-based technologies and products in an accelerated, cost-effective and IP-secure way. Since joining forces with ATDF, SVTC now offers an even more powerful suite of leading-edge equipment and services, including full-scale 8-inch (200mm) and 12-inch (300mm) process capabilities, advanced CMOS equipment, development support tools and commercialization services. SVTC's San Jose, Calif., and Austin, Texas, facilities deliver operational excellence and faster time to revenue, allowing customers to create real, manufacturing-ready solutions for rapidly growing markets such as MEMS/MOEMS, photovoltaics, biotech, novel memory, image sensors and high-voltage applications. More information can be found at www.svtc.com.

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